

ÉlanSC520 Microcontroller

Datasheet

This document amends the ÉlanSC520 Microcontroller Datasheet, order #22003B.

DOCUMENTATION DEFECTS AND CORRECTIONS

The following corrections apply:

On page 2 of the datasheet, add a new temperature range:

I = Industrial ($T_A = -40$ °C to +85°C) where: T_A = ambient temperature

Also on page 2, add a new row to the Valid Combinations table. The complete revised table is reproduced here:

Valid Com	binations
ÉlanSC520-100 ÉlanSC520-133	AC
ÉlanSC520-100	AI

On page 48, in the heading "Operating Ranges At Commercial Temperatures," change "Commercial" to "Commercial and Industrial."

Also on page 48, add a new operating range parameter, T_{AMBIENT}, for industrial ambient temperature. Minimum value: -40°C. Maximum value: +85°C

- On page 50, in the heading "DC Characteristics over Commercial Operating Ranges," change "Commercial" to "Commercial and Industrial."
- On page 56, in the section titled "Thermal Characteristics," change "The ÉlanSC520 microcontroller is..." to "ÉlanSC520 microcontroller commercial temperature devices are..." in the first sentence.
- On page 57, replace Table 15 with the updated version reproduced below. This new table adds a new row for T_{CASF} = 100°C.
- On page 59, in the heading "Switching Characteristics over Commercial Operating Ranges," change "Commercial" to "Commercial and Industrial."

Table 15. Maximum T_A for Plastic BGA Package with 6-Layer Board¹

T _{CASE}	CPU Clock Rate	Airflow (Linear Feet Per Minute)				
		0	200	400	600	800
85°C	133 MHz	67.3°C	69.8°C	71.3°C	72.2°C	72.7°C
	100 MHz	70.1°C	72.2°C	73.5°C	74.3°C	74.7°C
100°C ²	100 MHz	85.1°C	87.2°C	88.5°C	89.3°C	89.7°C

Notes:

- 1. The board type is described in the JEDEC standards document entitled Thermal Test Chip Guideline (Wire Bond Type Chip) at www.jedec.org. On the home page click on the link Free Standards and Docs, and then click on the document link JESD51-4 under JEDEC PUBLICATIONS.
- 2. $T_{CASE} = 100^{\circ}$ C data is for industrial temperature devices only.

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